



Click [here](#) for the 3D model.

Dimensions

Case Code	2D
L	8mm +/-0.38mm
W	4.4mm +/-0.2mm
H	6.2mm +/-0.38mm
S	1.9mm +/-0.38mm
F	3mm +/-0.2mm
K	4.8mm +/-0.38mm

Packaging Specifications

Packaging	Tray
Packaging Quantity	50

General Information

Series	TSP
Dielectric	Polymer Tantalum
Style	Stacked Chip
Description	SMD, Polymer, KO, Stacks, High Reliability
Features	High Reliability
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov .
SCIP Number	30e82d35-b509-48ec-8c77-2d5ec01b3abc
Termination	Solder Coated
Termination (Stack)	Solder Coated
AEC-Q200	No
MSL	3

Specifications

Capacitance	440 uF
Capacitance Tolerance	10%
Voltage DC	10 VDC (105C), 6.7 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	105°C
Dissipation Factor	10% 120Hz 25C
Failure Rate	N/A
Resistance	13 mOhms (100kHz 25C)
Leakage Current	440 uA (5min 25°C)
Testing and Reliability	10 Cycles Surge Current Testing At -55C +0C/-5C And +85C +/-5C After Voltage Aging